

CLAIM AMENDMENTS

1. (Currently Amended) A wet etching apparatus comprising:
a chemical-solution supply component for supplying a chemical solution ~~on~~ to a film
to be processed ~~on, the film being supported by a substrate, and~~
an ultraviolet-light radiating component for ~~radiating~~ irradiating the film with
ultraviolet light ~~to the film~~ through the chemical solution.

2. (Currently Amended) The wet etching apparatus according to claim 1, wherein the
ultraviolet-light radiating component radiates ultraviolet light having an energy higher than ~~a~~
binding energy of constituent molecules of the film.

3. (Currently Amended) The wet etching apparatus according to claim 1, further
comprising a drive unit for moving the ultraviolet-light radiating component, wherein the
ultraviolet-light radiating component is moved at a location 2 mm to 5 mm above a surface of
the film, ~~when radiating of~~ the film is being irradiated with the ultraviolet light.

4. (Currently Amended) The wet etching apparatus according to claim 1, wherein the
ultraviolet-light radiating component comprises:
a light source generating the ultraviolet light; ~~and~~
a storage component for accommodating the light source and having a light-
transmitting window for facing the film; and
~~wherein a nozzle in the chemical-solution supply component has a nozzle, disposed at~~
~~a side of a gap between the light-transmitting window and the film, the nozzle for~~
continuously supplying the chemical solution in the gap.

5. (Currently Amended) The wet etching apparatus according to claim 4, further
comprising a stage for holding the substrate, ~~wherein the stage including a pair of guides are~~
~~formed on the stage so as to be parallel to the nozzle and sandwich, for sandwiching the~~
substrate.

6. (Currently Amended) The wet etching apparatus according to claim 4, ~~wherein~~
including a layer of a surface-active agent is formed located at a surface of the light-
transmitting window and contacting the chemical solution.

7. (Currently Amended) The wet etching apparatus according to claim 4, wherein the chemical-solution supply component comprises:

a switching valve connected to the nozzle through a pipe and for switching between a supply of the chemical solution ~~or~~ and a supply of ultra-pure water;

a pipe for supplying the chemical solution and connected to the switching valve;
and

a pipe for supplying the ultra-pure water and connected to the switching valve.

8. (Currently Amended) A method for wet etching of a film, comprising:
supplying a chemical solution ~~on~~ to a film to be processed, the film being disposed on a substrate; and

~~radiating~~ irradiating the film with ultraviolet light ~~to the film~~ through the chemical solution.

9. (Currently Amended) The method for wet etching according to claim 8, ~~wherein~~ including supplying a the chemical solution and ~~radiating~~ irradiating the film with ultraviolet light ~~are simultaneously performed.~~

10. (Currently Amended) The method for wet etching according to claim 8, ~~wherein~~ the including irradiating the film with ultraviolet light having an energy higher than the binding energy of constituent molecules of the film ~~is radiated.~~

11. (Currently Amended) The method for wet etching according to claim 8, wherein the film is a high-k dielectric film ~~performed an annealing treatment~~ that has been annealed.